2SC5632

Silicon NPN epitaxial planar type

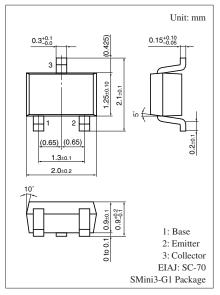
For high-frequency amplification and switching

■ Features

- High transition frequency f_T
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	8	V	
Emitter-base voltage (Collector open)	V_{EBO}	3	V	
Collector current	I_C	50	mA	
Collector power dissipation	P _C	150	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Marking Symbol: 2R

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 100 \ \mu A, I_E = 0$	15			V
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 2 \text{ V}, I_{C} = 0$			2	μΑ
Forward current transfer ratio	h_{FE}	$V_{CE} = 4 \text{ V}, I_C = 2 \text{ mA}$	100		350	_
h _{FE} ratio *	Δh_{FE}	h_{FE2} : $V_{CE} = 4 \text{ V}$, $I_{C} = 100 \mu A$	0.6		1.5	_
		h_{FEI} : $V_{CE} = 4 \text{ V}$, $I_C = 2 \text{ mA}$				
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 20 \text{ mA}, I_B = 4 \text{ mA}$			0.1	V
Transition frequency	f_T	$V_{CE} = 5 \text{ V}, I_{C} = 15 \text{ mA}, f = 200 \text{ MHz}$	0.6	1.1		GHz
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		1.0	1.6	pF
(Common base, input open circuited)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

^{2. *:} $\Delta h_{FE} = h_{FE2} / h_{FE1}$

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